

**IN THE CLAIMS:**

None of the claims have been amended herein. All of the pending claims 1 through 6 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

**Listing of Claims:**

1. (Previously Presented) A method of enhancing adhesion of a compound to a surface of a substrate comprising:  
providing a semiconductor substrate having the surface;  
finding irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate to locate irregularities; and  
roughening the surface of the semiconductor substrate when removing irregularities.
2. (Previously Presented) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate.
3. (Previously Presented) A method of enhancing adhesion of a material to a surface of a substrate comprising:  
providing a semiconductor substrate having the surface;  
determining irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate; and  
roughening the surface of the semiconductor substrate while removing irregularities.
4. (Previously Presented) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate.

5. (Previously Presented) A method for improving adhesion of a compound to a surface of a substrate comprising:

providing a semiconductor substrate having the surface;

locating irregularities to be removed from the semiconductor substrate by scanning the semiconductor substrate; and

roughening the surface of the semiconductor substrate while removing irregularities from the semiconductor substrate.

6. (Previously Presented) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate.